(19) World Intellectual Property Organization

International Bureau



US



(43) International Publication Date 15 May 2008 (15.05.2008) (10) International Publication Number WO 2008/057179 A3

(51) International Patent Classification: *H01L 21/335* (2006.01) *H01L 21/285* (2006.01)

(21) International Application Number:

PCT/US2007/022198

(22) International Filing Date: 18 October 2007 (18.10.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 11/557,354 7 November 2006 (07.11.2006)

(71) Applicant (for all designated States except US): RAYTHEON COMPANY [US/US]; 870 Winter Street, Waltham, MA 02451-1449 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): TABATABAIE, Kamal [US/US]; 651 Massapoag Avenue, Sharon, MA 02067 (US). HALLOCK, Robert, B. [US/US]; 52 Pond Street, Newton, NH 03858 (US).

(74) Agents: MOFFORD, Donald, F. et al.; Daly, Crowley, Mofford & Durkee, LLP, Suite 301a, 354a Turnpike St., Canton, MA 02021 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

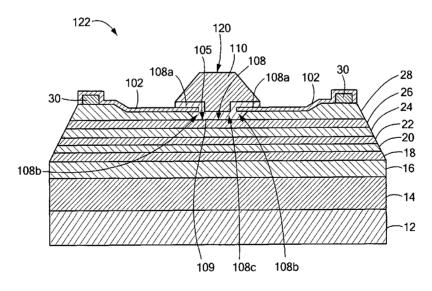
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

with international search report

(88) Date of publication of the international search report: 31 July 2008

(54) Title: ATOMIC LAYER DEPOSITION IN THE FORMATION OF GATE STRUCTURES FOR III-V SEMICONDUCTOR



(57) Abstract: A semiconductor structure having a recess (105) and a dielectric film(102) is disposed on and in contract with the semiconductor. The dielectric film has an aperture (104) therein. Portions of the dielectric film are disposed adjacent to the aperture and overhang underlying portions of the recess. An electric contact (108) has first portions (108a) thereof disposed on said adjacent portions of the dielectric film, second portions (108b) disposed on said underlying portions of the recess, with portions of the dielectric film being disposed between said first portion of the electric contact and the second portions of the electric contact, and third portions of the electric contact being disposed on and in contact with a bottom portion (109) of the recess in the semiconductor structure. The electric contact is formed by atomic layer deposition of an electrically conductive material over the dielectric film and through the aperture in such dielectric film.



INTERNATIONAL SEARCH REPORT

International application No

PCT/US2007/022198 CLASSIFICATION OF SUBJECT MATTER NV. H01L21/335 H01L21/285 According to International Patent Classification (IPC) or to both national classification and IPC B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) H01L Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched Electronic data base consulted during the international search (name of data base and, where practical, search terms used) EPO-Internal, INSPEC C. DOCUMENTS CONSIDERED TO BE RELEVANT Category' Citation of document, with indication, where appropriate, of the relevant passages Relevant to claim No. X JP 53 065671 A (MITSUBISHI ELECTRIC CORP) 1,2,8 12 June 1978 (1978-06-12) figure 2c 3-7,9-18Υ JESSEN G H ET AL: "Gate optimization of 3-6,9-18Algan/Gan HEMTs using WSi, Ir, Pd, and Ni Schottky contacts" GAAS IC SYMPOSIUM. 25TH. ANNUAL IEEE GALLIUM ARSENIDE INTEGRATED CIRCUIT SYMPOSIUM. TECHNICAL DIGEST 2003. SAN DIEGO, CA, NOV. 9 - 12, 2003, GAAS IC SYMPOSIUM - IEEE GALLIÚM ARSÉNIDE INTEGRATED CIRCUIT SYMPOSIUM, NEW YORK, NY : IEEE, US, 9 November 2003 (2003-11-09), pages 277-279, XP010673675 ISBN: 0-7803-7833-4 the whole document Further documents are listed in the continuation of Box C. See patent family annex. Special categories of cited documents : "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the 'A' document defining the general state of the art which is not considered to be of particular relevance invention *E* earlier document but published on or after the international "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone filing date 'L' document which may throw doubts on priority 'claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled document referring to an oral disclosure, use, exhibition or other means *P* document published prior to the international filing date but later than the priority date claimed in the art. "&" document member of the same patent family Date of the actual completion of the international search Date of mailing of the international search report 23 April 2008 06/05/2008 Name and mailing address of the ISA/ Authorized officer European Patent Office, P.B. 5818 Patentlaan 2 NL – 2280 HV Rijswijk Tel. (+31–70) 340–2040, Tx. 31 651 epo nl, Fax: (+31–70) 340–3016

Baillet, Bernard

INTERNATIONAL SEARCH REPORT

International application No PCT/US2007/022198

C(Continua		PC1/US2UC	777 022130
Category*	Citation of document, with indication, where appropriate, of the relevant passages		Relevant to claim No.
Υ	CHAE J ET AL: "Atomic Layer deposition of nickel by the reduction of preformed nickel oxide" ELECTROCHEMICAL AND SOLID-STATE LETTERS ELECTROCHEM. SOC USA, vol. 5, no. 6, June 2002 (2002-06), pages C64-C66, XP002477790 ISSN: 1099-0062 the whole document		3-6,9-18
Y A	US 2004/104443 A1 (AHN HOKYUN [KR] ET AL) 3 June 2004 (2004-06-03) paragraph [0019] - paragraph [0030]; figures 1A-1H	7 1-6,8-18	
A	ZHANG L C ET AL: "Refractory metal nitride rectifying contacts on GaAs" JOURNAL OF VACUUM SCIENCE & TECHNOLOGY B (MICROELECTRONICS PROCESSING AND PHENOMENA) USA, vol. 5, no. 6, November 1987 (1987-11), pages 1716-1722, XP002477791 ISSN: 0734-211X the whole document	·	4
Α .	US 2006/124962 A1 (UEDA TETSUZO [JP] ET AL) 15 June 2006 (2006-06-15) paragraph [0046] - paragraph [0050]; figure 1	•	1-7

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No PCT/US2007/022198

	Patent document cited in search report		Publication date	Patent family member(s)		Publication date
	JP 53065671	Α	12-06-1978	JP JP	1257702 C 59031866 B	29-03-1985 04-08-1984
	US 2004104443	A1	03-06-2004	CN KR	1507072 A 20040046277 A	23-06-2004 05-06-2004
,	US 2006124962	A1	15-06-2006	NONE		